



### ONFI Standards and What They Mean to Designers

Michael Abraham mabraham@micron.com Applications Engineering Manager Micron Technology, Inc.





## NAND Flash Inconsistencies Without ONFI

- Device identification using read ID
- Array architecture and addressing
- Command set
- Timing parameters
- ECC and endurance
- Factory-marked bad blocks
- Device behavior and status



Answering Questions

NAND Flash devices must answer basic questions to simplify software development and support:

- What is the page size (data and spare)?
- How many pages per block?
- How many blocks per die?
- How many die per CE#?
- Is the device multi-plane?
- How do I address the device?

- What advanced commands are supported?
- What timing parameters does this device support for normal and cache operations?
- How many bits of ECC are required?
- What is the block endurance?

## These are *not* answered by read ID, especially across multiple NAND vendors.

Santa Clara, CA USA August 2008

#### Micron



#### Qualification Time

No	Vendor Samples	Software/Firmware	NAND Driver	Product Level	Ship New NAND
Standard	New NAND	Updates	Testing	Testing	

- What are the effects of not having NAND standardization?
  - Long firmware/software development cycles and updates
  - Long test/verification cycles
  - Firmware/software changes for each new NAND Flash device
  - Products are slow to market
  - NAND Flash evolving faster than product lifecycles, which makes product continuity difficult if firmware/software must be rewritten to support new NAND devices





#### NAND Identification with ONFI

#### Read ID and the parameter page

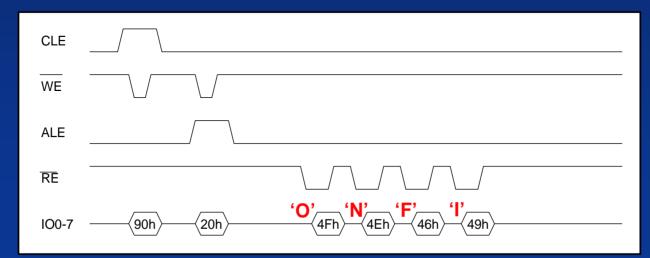
- Device identification
- Array architecture and addressing
- ECC and block endurance
- Timing modes
- Command set
- Bad block handling







- Read ID used today to identify each NAND device
- Using an address of 20h returns the ONFI signature and indicates that the polled device includes a parameter page







#### **Parameter Page**

- Parameter page describes the device's capabilities
- Sections within the parameter page
  - Revision information
  - Features
  - Manufacturer information
  - Memory organization
  - Device timing
  - Vendor-specific area

#### Memory Organization Block of Parameter Page

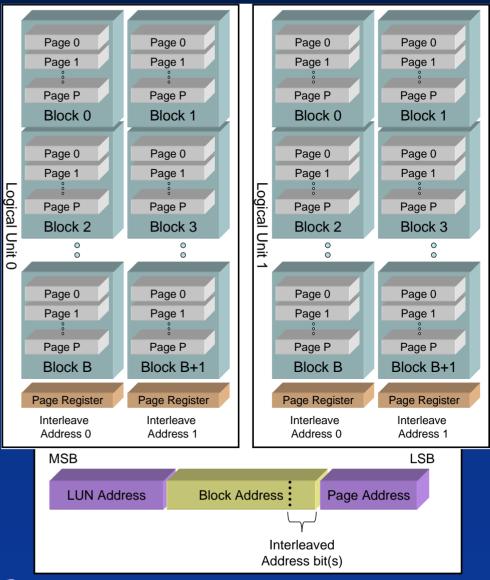
Number of data bytes per page Number of spare bytes per page Number of pages per block Number of blocks per logical unit (LUN) Number of logical units Number of address cycles Number of bits per cell **Block endurance** Number of programs per page Number of bits of ECC correction Interleaved addressing





### Architecture and Addressing

- ONFI uses abstraction because it defines behavior, not an implementation method
- The following ONFI terms are mapped to terms commonly used in NAND implementation:
  - Target: CE#
    - A packaged NAND device has one or more targets
    - A target is completely independent of other targets
  - Logical unit (LUN): die
    - A target has one or more LUNs
    - Each LUN is operationally independent of other LUNs on the same target
    - LUN address bits are above the block address bits
  - Interleaved address: plane
    - All interleaved operations must be the same type (program or erase)
    - Interleaved address bit(s) are the lowest order block address bits
    - Adding interleaved read to ONFI 2.1





#### **Command Set**

- Provides consistent, defined commands
- Advanced commands are optional ("O")
- The parameter page indicates whether optional commands are supported by the device
- Target level commands are indicated for the behavioral flow

		. et a	and a second	Target level
Command	O/M		2 <sup>nd</sup> Cycle	commands
Read	Μ	00h	30h	
Copyback Read	0	00h	35h	
Change Read Column	М	05h	E0h	
Read Cache Enhanced	0	00h	31h	
Read Cache	0	31h		
Read Cache End	0	3Fh		
Block Erase	Μ	60h	D0h	
Interleaved	0		D1h	
Read Status	Μ	70h		
Read Status Enhanced	0	78h		
Page Program	Μ	80h	10h	
Interleaved	0		11h	
Page Cache Program	0	80h	15h	
Copyback Program	0	85h	10h	
Interleaved	0	85h	11h	
Change Write Column	М	85h		
Read ID	М	90h		Y
Read Parameter Page	М	ECh		Y
Read Unique ID	0	EDh		Y
Get Features	0	EEh		Y
Set Features	0	EFh		Y
Reset	М	FFh		Y





#### Read Cache Enhanced (00-31h)

- Permits reading random pages anywhere on a LUN; important for computing applications
- Better performance than multi-plane page read since hidden <sup>t</sup>R < IO time</li>
- No page address restrictions, unlike multi-plane page read, which requires page address to be the same
- Command sequence:
  - Issue 00h-5A-30h (op A); wait for <sup>t</sup>R
  - Issue 00h-5A-31h (op B); wait <sup>t</sup>RCBSY
  - Read data from op A
  - Issue 3Fh; wait <sup>t</sup>RCBSY
  - Read data from op B





#### Read Status Enhanced (78h)

- Reads status on any LUN
- LUN status register bits
  - Bits 6 and 5 are generic
  - Bits 1 and 0 are specific to the selected interleaved address
- Changes data output between LUNs
  - Issue 00h command following read status enhanced for data output
  - Ignores interleaved address bits and only selects the LUN
  - Previously selected interleaved address outputs data
- Single command reduces burden of requiring a separate status command for each LUN (such as F1h, F2h, and so on)





#### Get Features (EEh), Set Features (EFh)

- Was not highly used in the ONFI 1.0 specification
- Used in ONFI 2.0 to cover setting of:
  - Output drive impedance
  - Interface type (legacy or DDR)
  - Interface timing mode
- Includes vendor-specific feature address space to handle the following:
  - OTP
  - R/B# pull-down strength
  - More...
- Reduces the need to add more vendor-specific instructions to the command set





#### **Timing Parameters**

Timing modes represent the timing parameters

Mode	<sup>t</sup> RC	<sup>t</sup> WC	Unit
0	100	100	ns
1	50	45	ns
2	35	35	ns
3	30	30	ns
4	25	25	ns
5	20	20	ns

- Supported timing modes are specified in the parameter page
- Provides consistent timing for controllers
- Controllers can operate slower than the published timing mode if not capable of fastest operation

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#### An Example: Timing Mode 4

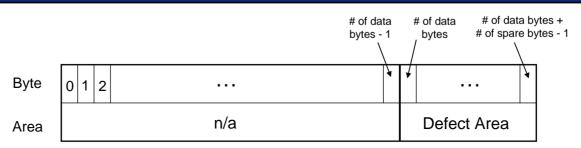
- Each parameter clearly specified
- All parameters' edges described in text, and most are drawn in figures

	Mode 4				Mode 4		
Parameter	Min	Max	Unit	Parameter	Min	Max	Unit
<sup>t</sup> ADL	70	_	ns	<sup>t</sup> RC	25	_	ns
<sup>t</sup> ALH	5	_	ns	<sup>t</sup> REA	_	20	ns
<sup>t</sup> ALS	10	_	ns	<sup>t</sup> REH	10	_	ns
<sup>t</sup> AR	10	_	ns	<sup>t</sup> RHOH	15	_	ns
<sup>t</sup> CEA	_	25	ns	<sup>t</sup> RHW	100	_	ns
ťCΗ	5	_	ns	<sup>t</sup> RHZ	_	100	ns
<sup>t</sup> CHZ	_	30	ns	<sup>t</sup> RLOH	5	_	ns
<sup>t</sup> CLH	5	_	ns	<sup>t</sup> RP	12	_	ns
<sup>t</sup> CLR	10		ns	<sup>t</sup> RR	20	_	ns
<sup>t</sup> CLS	10	_	ns	<sup>t</sup> RST	—	5/10/500	μs
<sup>t</sup> COH	15		ns	<sup>t</sup> WB	_	100	ns
<sup>t</sup> CS	20		ns	<sup>t</sup> WC	25	_	ns
<sup>t</sup> DH	5		ns	<sup>t</sup> WH	10	_	ns
<sup>t</sup> DS	10		ns	<sup>t</sup> WHR	60		ns
<sup>t</sup> FEAT		1	μs	<sup>t</sup> WP	12	_	ns
<sup>t</sup> IR	0		ns	tWW	100		ns





- Factory-marked bad blocks are now standardized for SLC and MLC, so both use the same algorithm
- The block is factory-marked bad if the first byte is 00h (or the first word is 0000h) in the "defect area" in the first or last page of the block
- Defect area

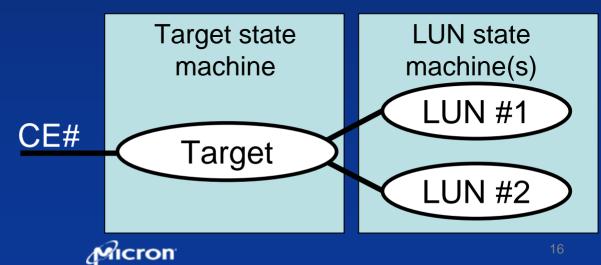


 MLC devices ship today without blocks being "pristine"; some defects may exist in good blocks



# **HISTORY** Device Behavior and Status

- Behavioral flow shows how the device operates
  - Target state machine
    - Handles read ID, read parameter page, and unique ID
    - Passes LUN operations to the correct LUN (based on address)
  - LUN state machine
    - One LUN state machine per LUN in the target
    - Handles anything that can be done in a multi-LUN operation, such as read page, program page, erase block
  - Provides consistent command and status behavior among vendors, greatly simplifying firmware for controllers





- No interleaved (multi-plane) read page
  - Coming in ONFI 2.1
- Not accepted by all NAND vendors
  - Would you rather write firmware for eight different NAND vendors or for the equivalent of three?
  - Micron extends open invitation to the last two NAND vendors to join ONFI
- ONFI describes device capabilities, but it doesn't eliminate nonsoftware-related issues
  - ONFI describes ECC requirements, but it can't make up for a lack of ECC support on the host controller
  - ONFI BA NAND (specification now available) provides a simpler NAND interface, including block management and ECC





## NAND Flash Consistencies After ONFI

- Device identification using the parameter page
- Array architecture and addressing
- Command set
- Timing modes and parameters
- ECC and endurance
- Factory-marked bad blocks
- Device behavior and status





## Other Concepts in the ONFI Specification

- Packaging pinout/ballouts
  - 48-pin Type-I TSOP
  - 63-ball BGA
  - 52-pad LGA with dual x8 interface
  - 100-ball BGA with dual x8 interface
- Electrical interface
- Power-on behavior
- Discovery and initialization
- Pin capacitance





- What are the effects of ONFI standardization?
  - Ability to write flexible firmware up front that supports various NAND architectures, page sizes, and vendors
  - Ability to shorten or eliminate the need for firmware/software updates for *each* new NAND device
  - Faster time to market





 ONFI specifications are publicly downloadable at <u>http://www.onfi.org/</u>

 ONFI membership is available to all; currently 85+ companies participate

There are currently no membership dues







#### **About Michael Abraham**

- Manager of Micron's NAND Flash Applications Engineering group
- B.S. in Computer Engineering from Brigham Young University



- Micron's technical representative in ONFI and JEDEC for NAND Flash
- Key role in defining and standardizing the new highspeed NAND interface within Micron and at ONFI

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Santa Clara, CA USA August 2008

